

Accordingly, the ultra-thin type camera module can be achieved. Further, even the image pickup device which includes the combination of the light-transmissible board 10 and the image pickup element 11 can be designed to be thinner than the conventional image pickup device 52 (see Fig. 6). Still further, the camera system 1 using the camera module 2 can be installed in an information terminal by using a smaller securing space because the thickness of the camera module 2 is reduced.

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IN THE CLAIMS:

Please enter the following amended claims:

- (saw) (b)*
1. (Amended) An image pickup device including:
a light-transmissible board having a wiring pattern formed on one surface thereof and containing
an optical filter; and
an image pickup element having a photodetecting portion formed on the same surface thereof,
said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible
board so that the photodetecting portion of the image pickup element is opposed to an area where the wiring
pattern is not formed.

3. (Amended) The image pickup device as claimed in claim 1, wherein a peripheral edge
portion of said image pickup element is sealed with resin.

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4. (Amended) A camera module including:
a light-transmissible board having a wiring pattern formed on one surface thereof and containing
an optical filter;
an image pickup element having a photodetecting portion formed on the same surface thereof;

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and

a lens unit mounted on the other surface of said light-transmissible board so as to be located
above said photodetecting portion of said image pickup element, said image pickup element being
mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting
portion of the image pickup element is opposed to an area where the wiring pattern is not formed.

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Cost